

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Original) A method of bonding two objects together, one of which has a polymer surface and the other has an electrically conductive or semiconductive surface, which method is characterized in that it comprises:
 - a) the electrografting of an organic film onto the conductive or semiconductive surface; and then
 - b) an operation of bonding the polymer surface to the conductive or semiconductive surface thus grafted.
2. (Original) The method as claimed in claim 1, characterized in that the electrografting of the organic film is electroinitiated grafting.
3. (Original) The method as claimed in claim 2, characterized in that the organic film is a polymer film.
4. (Original) The method as claimed in claim 3, characterized in that the polymer film is obtained from monomers and/or prepolymers that are partly or completely functionalized by vinyl groups.
5. (Original) The method as claimed in claim 4, characterized in that the polymer film is obtained from a vinyl monomer chosen from acrylonitrile, methacrylonitrile, acrylates and methacrylates, acrylamides and methacrylamides, cyanoacrylates, acrylic acid and methacrylic acid, styrene, vinyl halides, N-vinylpyrrolidone, 2-vinylpyridine, 4-vinylpyridine and vinyl-terminated telechelic compounds.

6. (Original) The method as claimed in claim 3, characterized in that the polymer film is obtained from monomers and/or prepolymers that are partly or completely functionalized by cyclic groups that can be cleaved by nucleophilic or electrophilic attack.

7. (Original) The method as claimed in claim 2, characterized in that the organic film is obtained from diazonium, sulfonium, phosphonium or iodonium salts, or mixtures thereof.

8. (Currently Amended) The method as claimed in ~~any one of the preceding claims~~ claim 1, characterized in that the bonding operation consists of hotmelt bonding or cold bonding or a combination of the two.

9. (Original) The method as claimed in claim 8, characterized in that the cold bonding is carried out by means of a substance capable of dissolving or swelling the polymer surface to be bonded and the organic film electrografted onto the conductive or semiconductive surface.

10. (Currently Amended) The method as claimed in ~~any one of the preceding claims~~ claim 1, characterized in that the polymer constituting the polymer surface is chosen from polyethylenes, polypropylenes, polystyrenes, polyacrylonitriles, polysiloxanes, polyesters, polyorthoesters, polycaprolactones, polybutyrolactones, polyacrylics, polymethacrylics, polyacrylamides, epoxide resins, copolymers thereof and blends thereof.

11. (Currently Amended) The method as claimed in ~~any one of the preceding claims~~ claim 1, characterized in that the polymer constituting the polymer surface is a hotmelt polymer.

12. (Currently Amended) The method as claimed in ~~any one of the preceding claims~~ claim 1, characterized in that the polymer surface is a polymer film coating a conductive or semiconductive material.

13. (Currently Amended) ~~The application of the method as defined in any one of claims 1 to 12 to the manufacture or renovation of composites~~ A method of manufacturing or renovating composites intended for the aerospace, aeronautical, automotive, biomedical, microelectronics and microsystems industries ,which comprises a step consisting in bonding two objects together by the method of claim 1.

14. (Currently Amended) ~~The application of the method as defined in any one of claims 1 to 12 to the manufacture of~~ A method of manufacturing implantable surgical and medical instruments ,which comprises a step consisting in bonding two objects together by the method of claim 1.

15. (Currently Amended) ~~The application of the method as defined in any one of claims 1 to 12 to the assembly of~~ A method of assembling sensitive components of microsystems which comprises a step consisting in bonding two objects together by the method of claim 1 ~~or to the packaging of microsystems.~~

16. (Original) A structure comprising two objects, one of which has an electrically conductive or semiconductive surface and the other has a polymer surface, these surfaces being bonded to each other via an organic film with a thickness of less than 1 μm .

17. (New) A method of packaging of Microsystems, which comprises a step consisting in bonding two objects together by the method of claim 1.